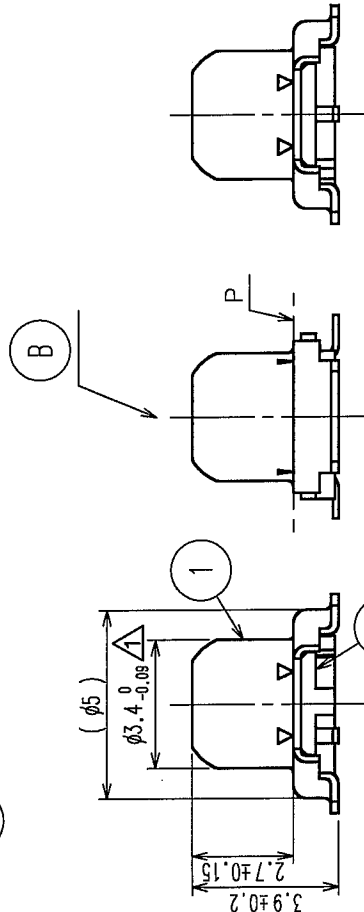
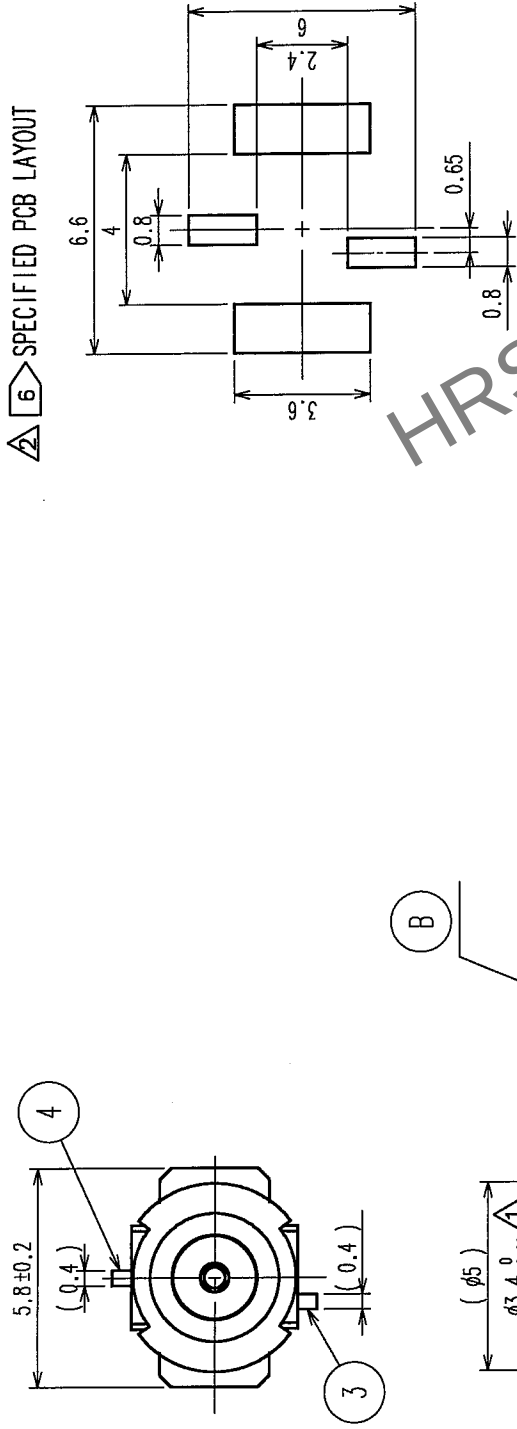
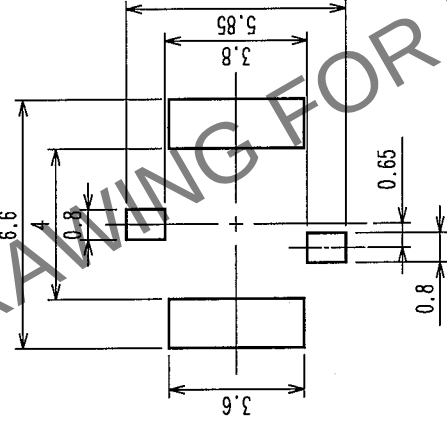


COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE	COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE
1	RE-J-01473	K.HIDAR.KANO		'99.11.19					
6	RE-J-02231	D.Y.R.K		'04.9.25					

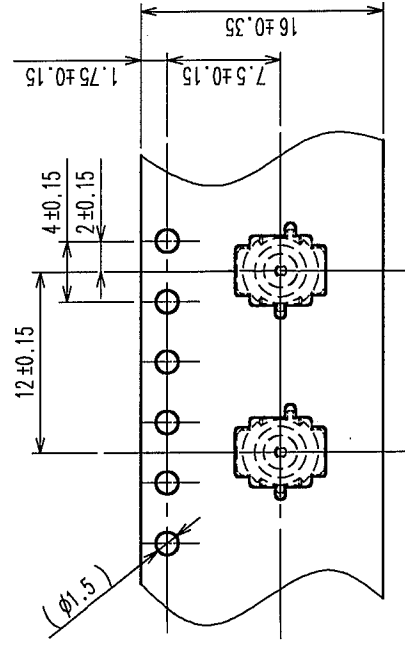
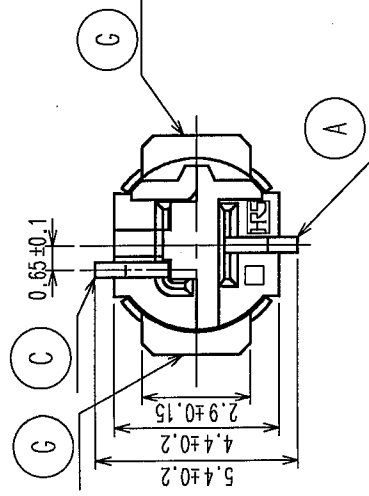
6 SPECIFIED PCB LAYOUT



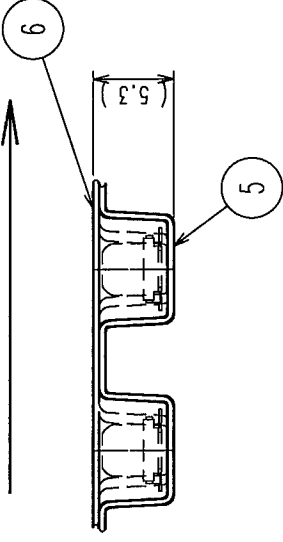
6 SPECIFIED STENCIL PLATE (t=0.13mm)



TAPE AND REEL PACKING (FREE)

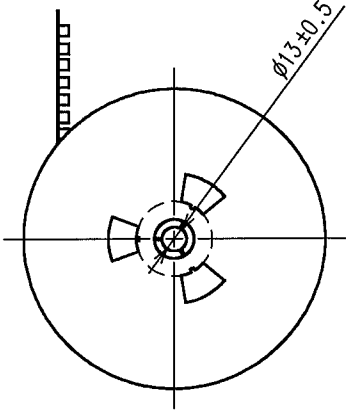


THE DIRECTION OF PULLING OUT.

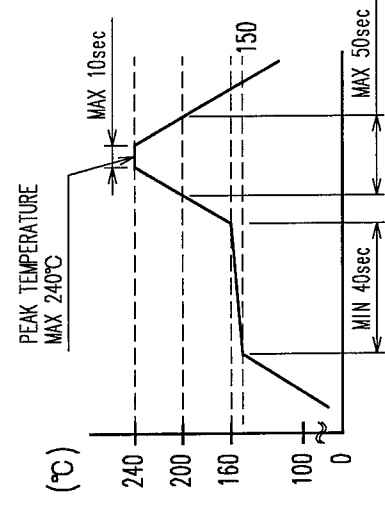


1500 PIECES PER REEL.

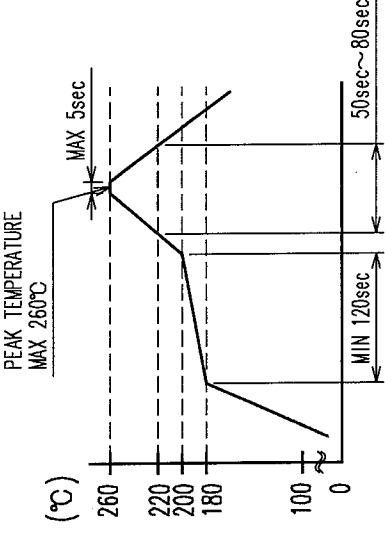
THE DIRECTION OF PULLING OUT.



RECOMMENDED REFLOW TEMPERATURE PROFILE FOR TIN-LEAD SOLDER

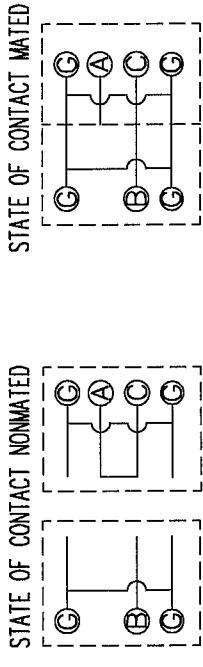


6 SPECIFIED REFLOW TEMPERATURE PROFILE FOR LEAD-FREE SOLDER



NOTE 1. USE THIS PRODUCT WITH MS-147-HRMJ-1 AND EQUIVALENT CONTACT MATED.
FOR THE USE OF MS-147-HRMJ-1 AND EQUIVALENT, PUSH THEM ON THE POSITION P.
USE WITH THE STRUCTURE WHICH ALWAYS KEEP IN TOUCH TO THE POSITION P OR WITH LOCK STRUCTURE.

2. COAXIAL SWITCH CIRCUIT SHALL BE AS FOLLOWS:



3. LEAD CO-PLANARITY TO BE 0.13 mm MAX.

4. THIS PRODUCT IS IMPOSSIBLE TO WASH.

5. AVOID SHOCKING TO THIS PRODUCT DIRECTLY.

6 PCB LAYOUT, STENCIL PLATE AND REFLOW TEMPERATURE PROFILE ARE SPECIFIED FOR LEAD-FREE.

NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS
3	BERYLLIUM COPPER	SMT AREA: GOLD 0.03~0.07μ	6	PS	
2	POLYAMIDE	CONTACT AREA: GOLD 0.5μ	5	PS	
1	PHOSPHOR BRONZE	BLACK UL94HB	4	BERYLLIUM COPPER	SMT AREA: GOLD 0.03~0.07μ CONTACT AREA: GOLD 0.5μ

CODE NO. (OLD)	DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED
	K.HIDA	K.HIDA	K.KANO	Y.MIYAKE	
	99.9.21	99.9.21	99.9.21	99.9.21	

DRAWING NO.	PART NO.
EDC3-180145-01	MS-147(06)

SCALE	CODE NO.
5 : 1	CL358-0150-5-06

UNITS	FORM NO.
mm	NO.229